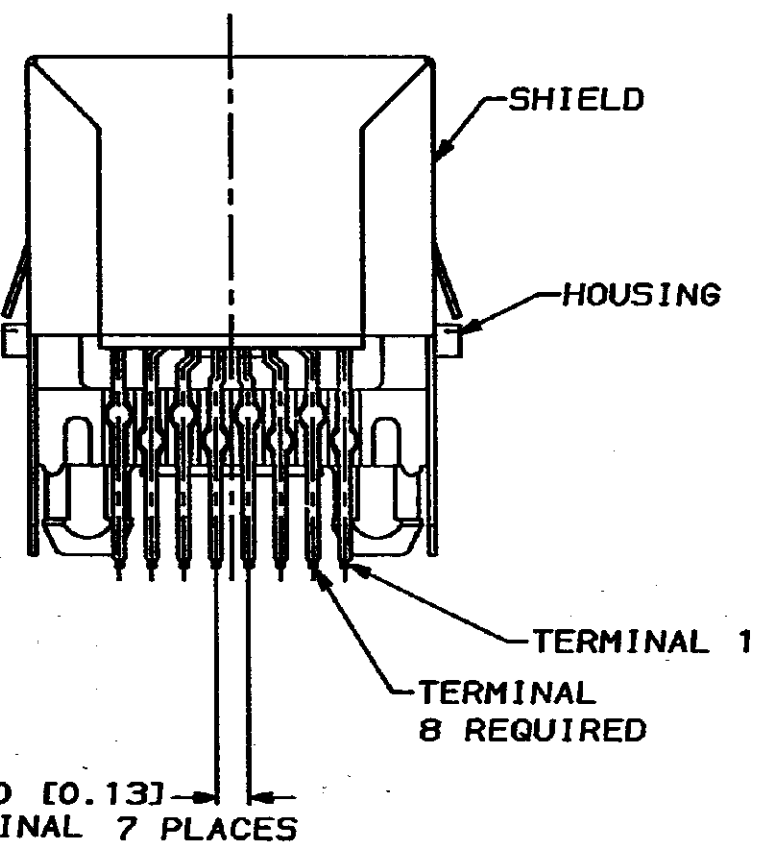
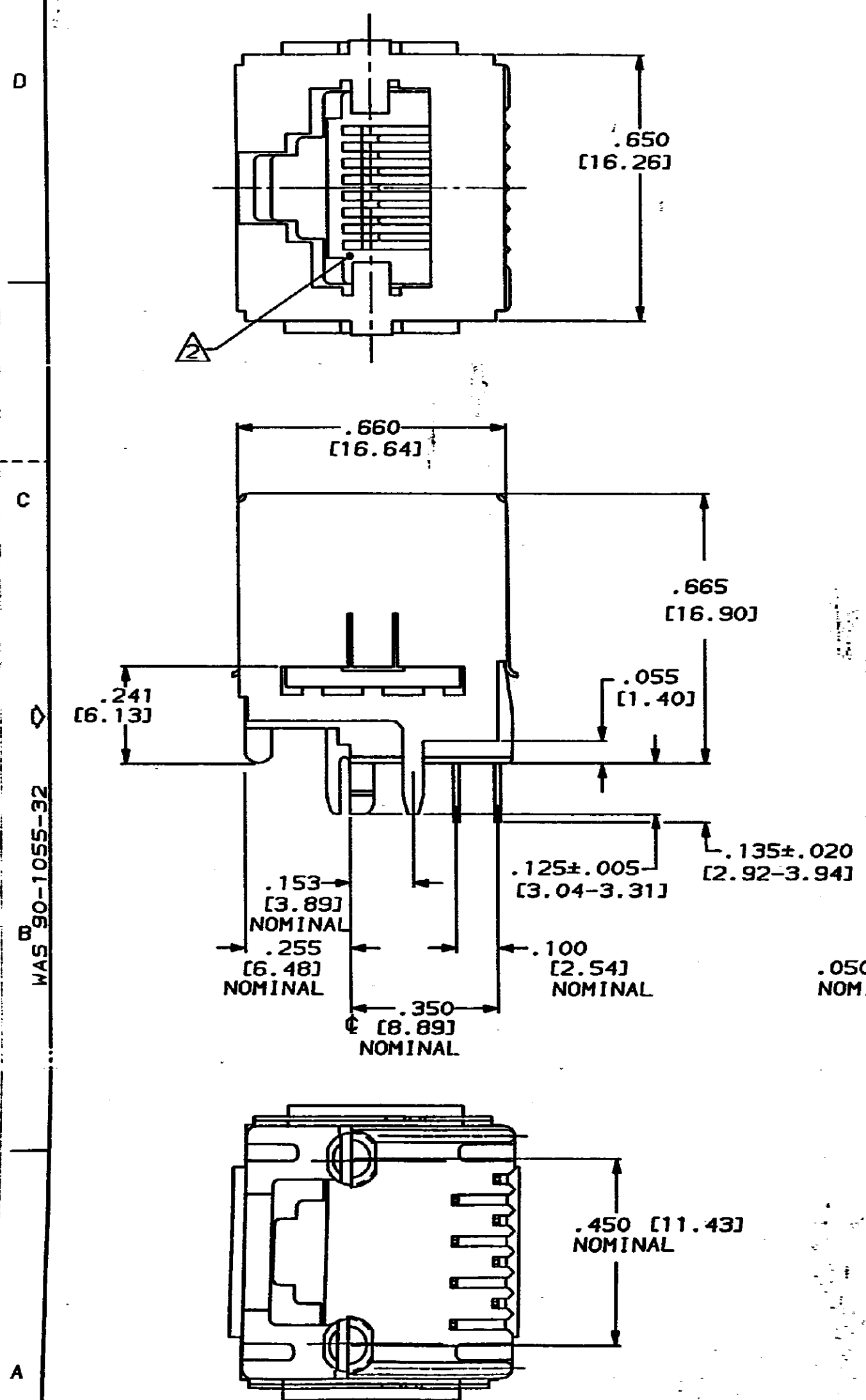
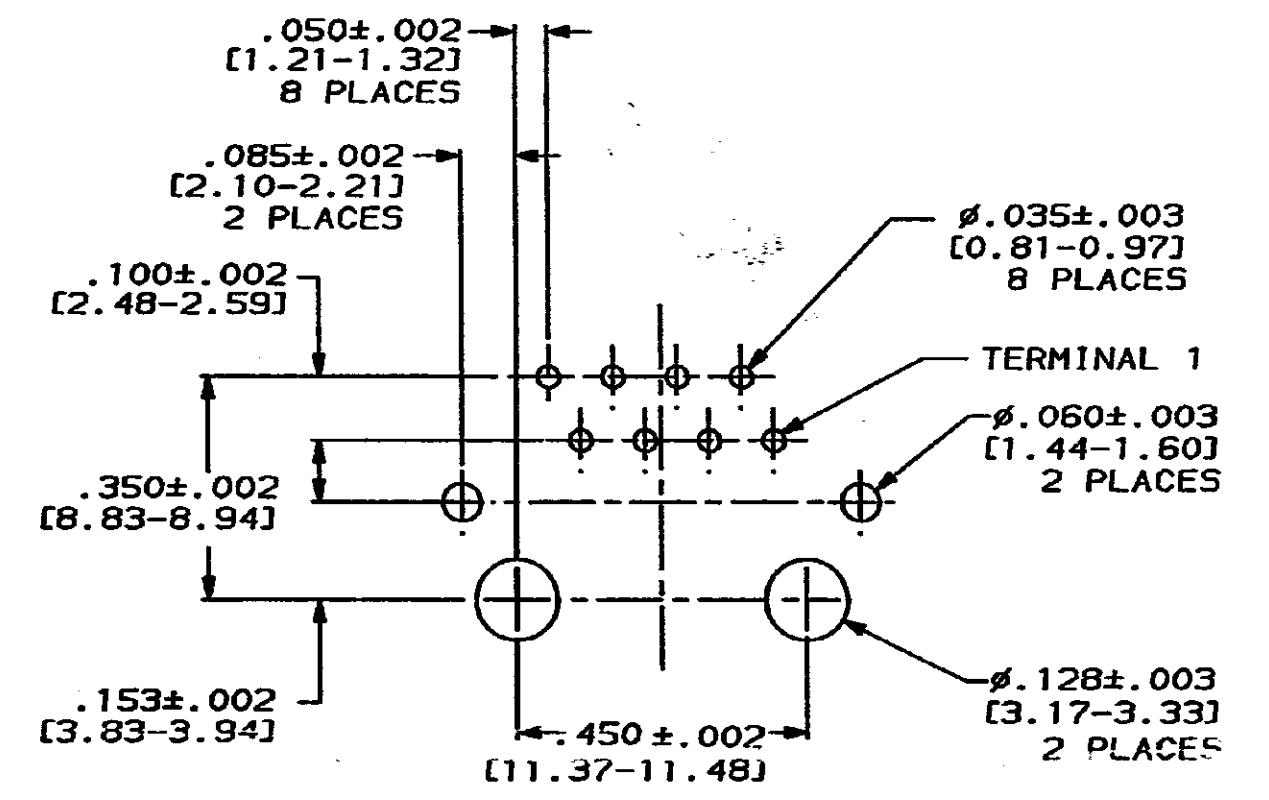


DRAWING MADE IN THIRD ANGLE PROJECTION
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LOC	DIST	P	F	ZONE	LTR	REVISIONS	DATE	APPD
AA	22				A	REV, ECN AA-8462	5-5-92	RS



- 1. MATERIAL: HOUSING- POLYESTER MOLDING COMPOUND, BLACK. TERMINALS- .0138 [0.350] THICK PHOS BRONZE PLATED WITH .000050 [1.27um] MINIMUM THICK GOLD IN LOCALIZED AREA AND .000150 [3.81um] MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER .000050 [1.27um] MINIMUM THICK NICKLE UNDERPLATE. SHIELD- COPPER ZINC ALLOY PLATED WITH .000080 [2.03um] MINIMUM THICK TIN-LEAD OVER .000100 [2.54um] MINIMUM THICK COPPER UNDERPLATE.
- 2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3. FOR APPLICATION INFORMATION SEE AMP SPECIFICATION 114-2048.
- 4. FOR PERFORMANCE REQUIREMENTS SEE AMP SPECIFICATION 108-1163.
- 5. DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 6. BULK PACKAGED IN A TRAY.
- 7. DIMENSIONS IN BRACKETS [] ARE IN MILLIMETERS.



VIEW SHOWN IS CIRCUIT (NONCOMPONENT) SIDE OF PC BOARD HOLE LAYOUT

CAD DRAWINGS
 THIS DRAWING WAS CREATED ON A COMPUTER AIDED DESIGN (CAD) SYSTEM TO INSURE THE INTEGRITY OF THE DATA BASE ALL CHANGES/REVISIONS MUST BE MADE ON THE CAD SYSTEM.

DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN INCHES [mm] TOLERANCES ON:		DR RB. INZERILLO 12-03-91		557484-1 PART NO	
2 PLC DEC ±	△	CHK D. HUSSEY 3-24-92	AMP AMP Incorporated Harrisburg, PA 17105-3608		
3 PLC DEC ±	△	APPD J. TONEY 4-2-92	NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH PANEL STOPS, PANEL & PCB GROUNDS		
ANGLES ±	△	APPD J. TONEY 4-2-92	PRODUCT SPEC		
MATERIAL	△	FINISH	APPLICATION SPEC	SIZE C 00779	DRAWING NO 557484
	△			SCALE 4:1	SHEET 1 OF 1

CAD CUSTOMER DRAWING